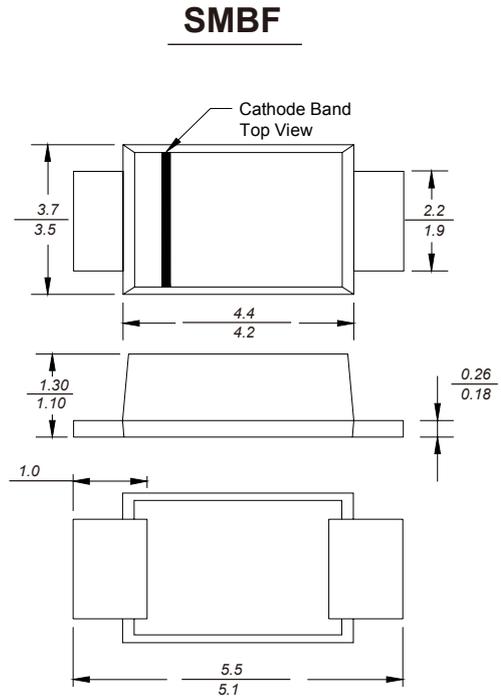


### FEATURES

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- For surface mounted applications
- Ultra fast switching for high efficiency
- Low reverse leakage
- Built-in strain relief, ideal for automated placement
- High forward surge current capability
- High temperature soldering guaranteed 260°C/10 seconds at terminals
- Glass passivated chip junction

### MECHANICAL DATA

- Case:** SMBF molded plastic body over passivated chip
- Terminals:** Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity:** Color band denotes cathode end
- Mounting Position:** Any



Dimensions in inches and (millimeters)

### MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

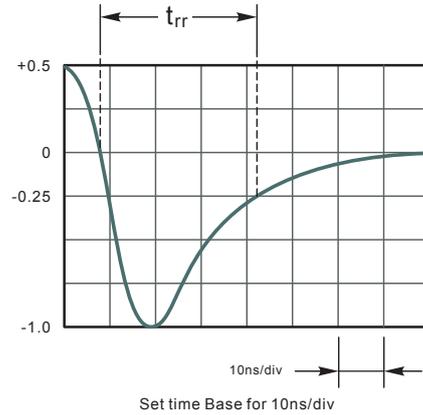
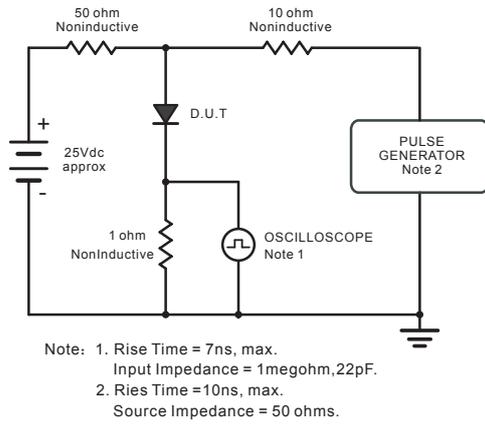
Ratings at 25°C ambient temperature unless otherwise specified.  
Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

	SYMBOLS	ES2ABF	ES2BBF	ES2CBF	ES2DBF	ES2EBF	ES2GBF	ES2JBF	UNITS
Maximum repetitive peak reverse voltage	$V_{RRM}$	50	100	150	200	300	400	600	V
Maximum RMS voltage	$V_{RMS}$	35	70	105	140	210	280	420	V
Maximum DC blocking voltage	$V_{DC}$	50	100	150	200	300	400	600	V
Maximum average forward rectified current at $T_L=75^\circ\text{C}$	$I_{(AV)}$	2.0							A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load	$I_{FSM}$	50.0							A
Maximum instantaneous forward voltage at 2.0A	$V_F$	0.95			1.25		1.7		V
Maximum DC reverse current at rated DC blocking voltage	$I_R$	5.0 50.0							$\mu\text{A}$
Maximum reverse recovery time (NOTE 1)	$t_{rr}$	35							ns
Typical junction capacitance (NOTE 2)	$C_J$	60.0							pF
Typical thermal resistance (NOTE 3)	$R_{\theta JA}$	65.0							$^\circ\text{C/W}$
Operating junction and storage temperature range	$T_J, T_{STG}$	-55 to +150							$^\circ\text{C}$

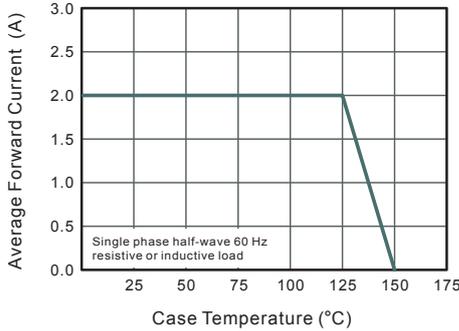
- Note: 1. Reverse recovery condition  $I_F=0.5\text{A}, I_R=1.0\text{A}, I_{rr}=0.25\text{A}$
- 2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
- 3. P.C.B. mounted with 0.2x0.2" (5.0x5.0mm) copper pad areas



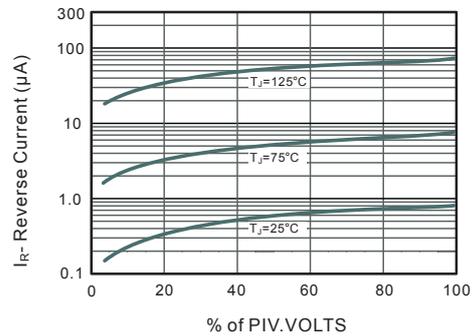
**Fig.1 Reverse Recovery Time Characteristic And Test Circuit Diagram**



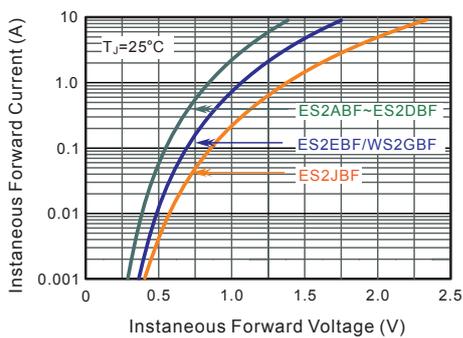
**Fig.2 Maximum Average Forward Current Rating**



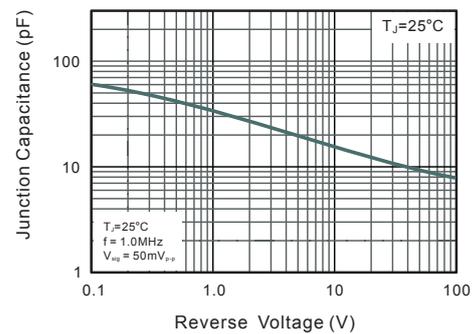
**Fig.3 Typical Reverse Characteristics**



**Fig.4 Typical Forward Characteristics**



**Fig.5 Typical Junction Capacitance**



**Fig.6 Maximum Non-Repetitive Peak Forward Surge Current**

